



Material Content Data Sheet



Sales Product Name		ICE3A2065Z		Issued		27. September 2017		
MA#		MA001118210						
Package		PG-DIP-7-4		Weight*		652.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.194	0.80	0.80	7957	7957
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		298	
	non noble metal	iron	7439-89-6	3.884	0.60		5951	
wire	non noble metal	copper	7440-50-8	157.726	24.16	24.80	241625	247948
	noble metal	gold	7440-57-5	0.250	0.04	0.04	384	384
encapsulation	organic material	carbon black	1333-86-4	1.426	0.22		2185	
	plastics	epoxy resin	-	46.119	7.07		70652	
	inorganic material	silicondioxide	60676-86-0	427.911	65.54	72.83	655530	728367
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9896	9896
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2927	2927
glue	plastics	epoxy resin	-	0.247	0.04		378	
	noble metal	silver	7440-22-4	1.399	0.21	0.25	2143	2521
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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